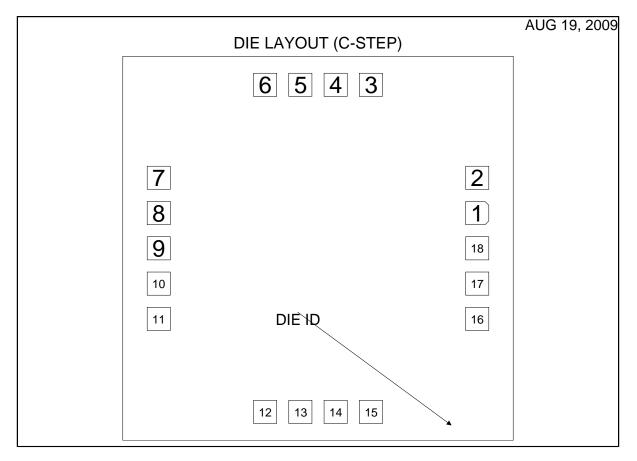


DS90C032 MDR MCD3050A LVDS QUAD CMOS DIFFERENTIAL LINE RECEIVER



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | | |
|---------------------------|---------------------------|-------------------------|-------------------|--|
| Physical Die | DS90C032 | Bond Pad Opening | 91.76µm x 91.92µm | |
| Identification | | Size (min) | | |
| Die Step | С | Bond Pad Metalization | AL1.0%SI0.5%CU | |
| Physical Attributes | | Passivation | PECVDOX NITRIDE | |
| Wafer Diameter | 150mm | Back Side Metal | Bare Back | |
| Die Size (Drawn) | 1549.4µm x 1524.0µm | Back Side Connection | Floating or GND | |
| | 61.0mils x 60.0mils | | | |
| Thickness | 304.8µm Nominal | | | |
| Min Pitch | 139.84µm | | | |
| Note: All values are roun | ded to the nearest micron | | | |
| Special Assembly Requi | rements: | | | |
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| Signal Name | Pad Number | X/Y Coordinates | | Pad Size | | |
|-------------|------------|-----------------|------|----------|---|----|
| | | Х | Y | Х | | Y |
| RIN 1- | 1 | 632 | 140 | 92 | х | 92 |
| RIN 1+ | 2 | 632 | 280 | 92 | х | 92 |
| ROUT 1 | 3 | 210 | 649 | 92 | х | 92 |
| EN | 4 | 70 | 649 | 92 | х | 92 |
| ROUT2 | 5 | -70 | 649 | 92 | х | 92 |
| RIN 2+ | 6 | -210 | 649 | 92 | х | 92 |
| RIN 2- | 7 | -632 | 280 | 92 | х | 92 |
| GND | 8 | -632 | 140 | 92 | х | 92 |
| GND | 9 | -632 | 0 | 92 | х | 92 |
| RIN 3- | 10 | -632 | -140 | 92 | х | 92 |
| RIN 3+ | 11 | -632 | -280 | 92 | х | 92 |
| ROUT3 | 12 | -210 | -649 | 92 | х | 92 |
| EN* | 13 | -70 | -649 | 92 | х | 92 |
| ROUT4 | 14 | 70 | -649 | 92 | х | 92 |
| RIN 4+ | 15 | 210 | -649 | 92 | х | 92 |
| RIN 4- | 16 | 632 | -280 | 92 | х | 92 |
| VCC | 17 | 632 | -140 | 92 | х | 92 |
| VCC | 18 | 632 | 0 | 92 | х | 92 |



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| Notes | | | | | | | |
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